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Electronic Patent Application Submission
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Application ID: 09687048
Title of Invention: LEADFRAME AND
SEMICONDUCTOR PACKAGE WITH
IMPROVED SOLDER JOINT
STRENGTH
First Named Inventor: Kuri-shi Lee
Domestic/Foreign Application: Domestic Application
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Confirmation Number: 1120
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Submission Type: Information
Disclosure Statement

Application Number: 09/687,048
Attorney Docket Number: AMKOR-052A

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

First Named Inventor: Kuri-shi Tae Heon Lee

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Attached Files:

us-information-disclosure-statement

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Comments:



Electronic Information Disclosure Statement

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

Application:



09/687048

Confirmation: 1120

Applicant(s): Kuri-shi Lee

Docket

Number:

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Group Art

Unit:

2814

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US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents